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The chemistry inside innovation™

HOSTAFORM® M30RS

HOSTAFORM®

Hostaform® M30RS is an acetal copolymer targeted for extrusion shapes (rod, bar, plate, etc.) free of center porosity in large diameters and thicknesses with improved processing. Chemical abbreviation according to ISO 1043-1: POM.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	2.2	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.2	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2500	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	60	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	12	%	ISO 527-1/-2
Flexural modulus	2400	MPa	ISO 178
Flexural stress at 3.5%	68	MPa	ISO 178
Flexural strain at failure	3.5	%	ISO 178
Compressive stress at 1% strain	26	MPa	ISO 604
Charpy impact strength, 23°C	250	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	190	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	10	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.38[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	92	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Density	1410	kg/m^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding, Calendering, Compression moulding
Delivery form	Pellets
Additives	Release agent

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Film extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects on the extruded film. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 3 Hrs. at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.35%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and melt homogeneity. The design should be approximately 35% each for feed and metering sections with the remaining 30% as the transition zone.

Melt temperature: 160-220 C (320-430 F)

Postprocessing

Postprocessing conditioning or moisturizing is not required.

Other extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying is 3 hours at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.35%

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and uniform melt homogeneity. The design should be approximately 35% each for the feed and metering sections with the remaining 30% as transition zone.

Melt temperature 180-220 C (355-430F)

Postprocessing

Postprocessing conditioning or moisturizing are not required. For thick walled sections (>3mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)

Annealing time: 10 min/mm thickness

Profile extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can cause surface defects on the extrusion. For better uniformity especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 3 Hrs. at 80 C (180 F). Desiccant hopper dryers are not required. Max. moisture content = 0.035%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio of at least 3:1 and preferably 4:1 to assure good melting and melt homogeneity. The design should be approximately 35% each for feed and metering sections with the remaining 30% as the transition zone.

Melt temperature: 180-220 C (360-430 F).

Postprocessing

Postprocessing or moisturizing is not required. For thick walled extrusions (>3 mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)
Annealing time: 10 min/mm thickness

Sheet extrusion

Preprocessing

Drying is generally not required because Celcon materials are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to surface defects. For better uniformity in sheet extrusion especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying is 3 hours at 80 C (180 F). Desiccant hopper dryers are not required. Max. water content = 0.35%.

Processing

Standard extruders with a length to diameter ratio of at least 20:1 are recommended. The screw should be a high compression ratio (at least 3:1 and preferably 4:1) to assure good melting and uniform melt homogeneity. The screw design should be approximately 35% each for the feed and metering sections with the remaining 30% as the transition zone.

Melt temperature 180-190 C (355-375 F).

Postprocessing

Postprocessing conditioning or moisturizing is not required. For thick walled sections (>3mm or 1/8 in.), annealing is recommended to reduce internal stresses.

Annealing temperature: 130-140 C (265-285 F)

Annealing time: 10 min/mm wall thickness

Blow molding

Preprocessing

Consult product information services.

Processing

Consult product information services.

Postprocessing

Consult product information services.

Calandering

Preprocessing

Consult product information services.

Processing

Consult product information services.

Postprocessing

Consult product information services.

Compression molding

Preprocessing

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Consult product information services.

Processing

Consult product information services.

Postprocessing

Consult product information services.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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